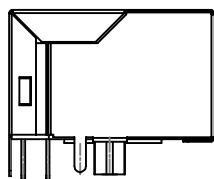


REACH & RoHS  
COMPLIANT

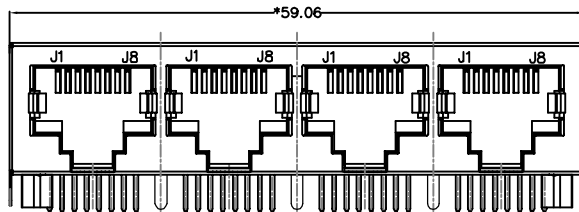
REV.	ECN / DESCRIPTION	BY	DATE
A0	NEW	MQ.Qu	2018.01.11



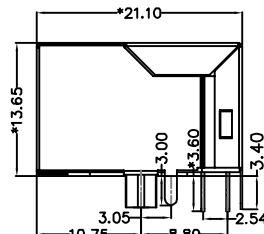
TOP VIEW



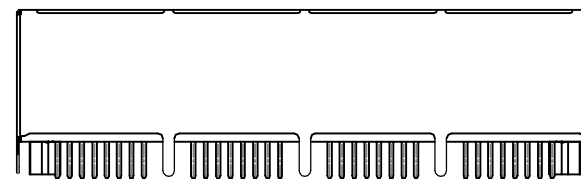
LEFT SIDE VIEW



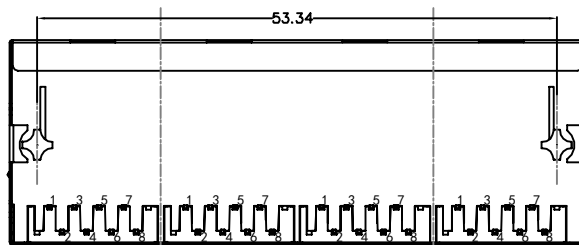
FRONT VIEW



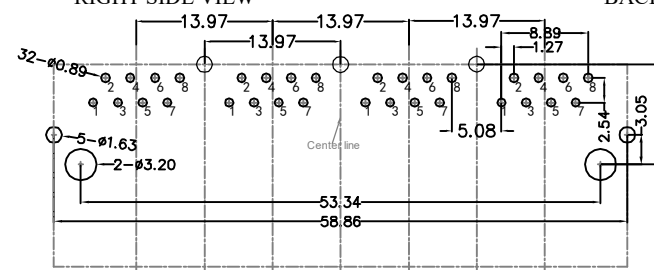
RIGHT SIDE VIEW



BACK VIEW




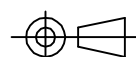
BOTTOM VIEW



RECOMMENDED PCB LAYOUT  
VIEWED FROM COMPONENT SIDE

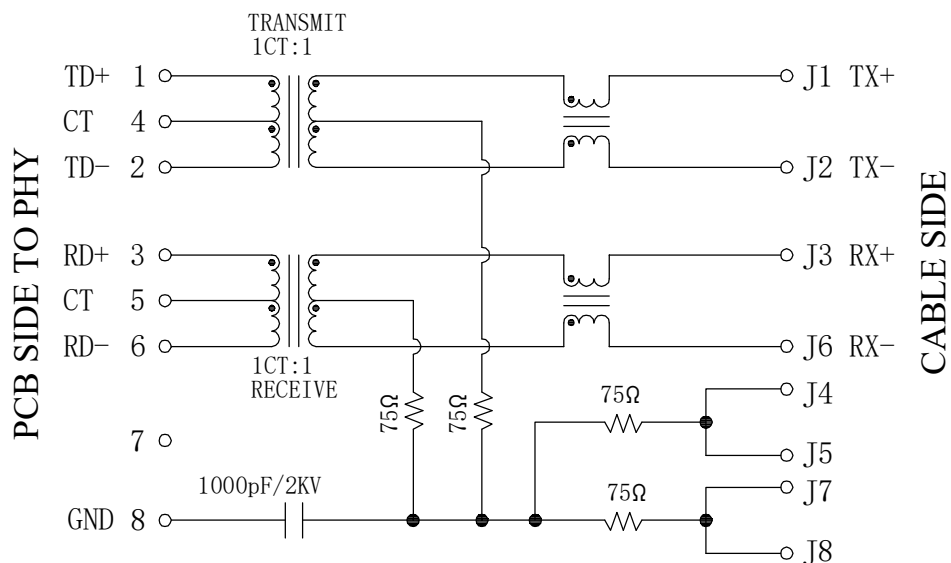
**MATERIAL:**  
 HOUSING: PBT,UL94V-0,BLACK.  
 TERMINALS BRACKET: PBT,UL94V-0,BLACK.  
 SHIELD: C2680,T=0.20MM,NICKEL PLATING ON ALL AREA.  
 TERMINAL: PHOSPHOR BRONZE C5210,T=0.35MM,  
 6U" GOLD PLATING ON CONTACT AREA.

**MECHANICAL:**  
 DURABILITY: 750 CYCLES MIN.  
 MATING FORCE: 23N MAX.  
 OPERATING TEMPERATURE: -40°C~+85°C.  
 STORAGE TEMPERATURE: -40°C~+85°C.  
 ALL CRITICAL DIMENSIONS WITH "\*"

 <b>苏州沃虎电子科技有限公司</b> Su Zhou Wo Hu Electronic Tech.Co.,Ltd.	TITLE: TAB-DOWN 1X4 100BASE	SIZE A4	UNITS MM[INCH]	GENERAL TOLERANCES UNLESS SPECIFIED		APPROVED BY: JP.Gong
	PART NO.: SYT114B002GWA1D3	SACLE 1:1	REV A0	x±0.35	x°±3.0°	CHECKED BY: TW.Xu
	REMARK:	SHEET 1/3		.xx±0.25	.xx°±1.5°	DESIGND BY: MQ.Qu
				.xxx±0.10	.xxx°±1.0°	



REACH & RoHS  
COMPLIANT

REV.	ECN / DESCRIPTION	BY	DATE
A0	NEW	MQ.Qu	2018.01.11



**Electrical:**

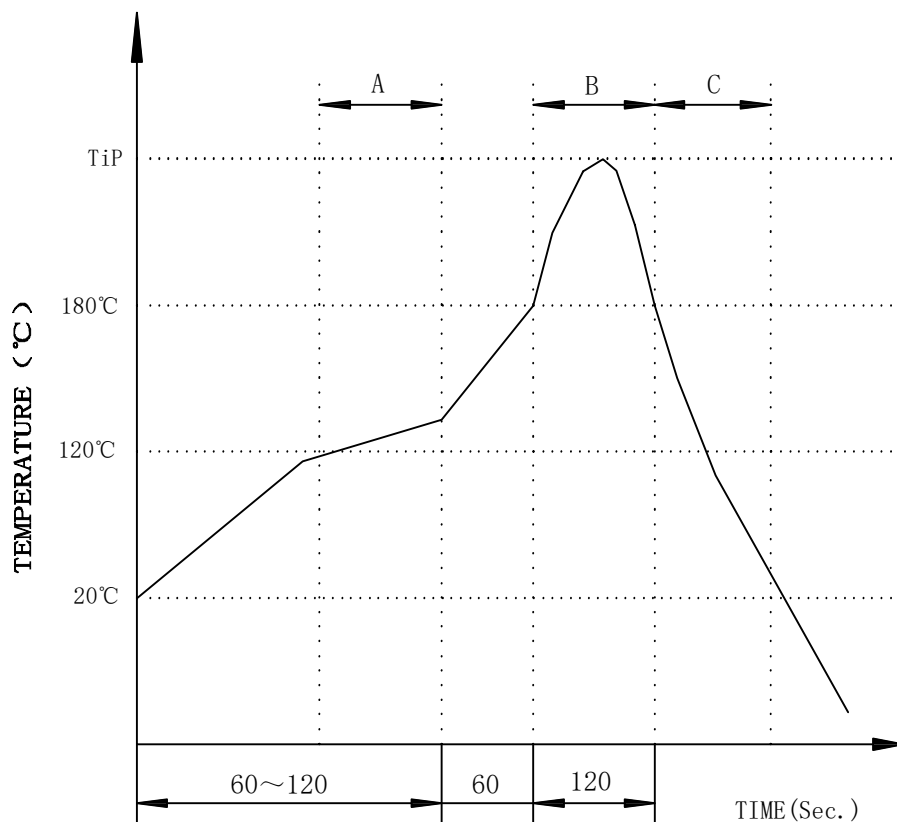
- Turn ratio: 1~2: J1~J2=1CT:1CT(±2%).  
3~6: J3~J6=1CT:1CT(±2%).
- OCL: 350uH Min. at 100KHz 100mV 8mA DC.
- Insertion Loss: -1.0 dB Max 1~100MHz.
- Return loss: -20dB Min 1~10MHz;  
-16dB Min 10~30MHz.  
-12dB Min 30~60MHz.  
-10dB Min 60~80MHz.
- Cross talk: -40dB Min 1~30MHz;  
-35dB Min 30~60MHz;  
-30dB Min 60~100MHz;
- CMR: -30dB Min 1~100MHz;
- Hi-Pot: 1500V AC & 2250V DC  
6S 1mA PRI TO SEC

 <b>苏州沃虎电子科技有限公司</b> Su Zhou Wo Hu Electronic Tech.Co.,Ltd.	TITLE: TAB-DOWN 1X4 100BASE	SIZE A4	UNITS MM[INCH]	GENERAL TOLERANCES UNLESS SPECIFIED		APPROVED BY: JP.Gong
	PART NO.: SYT114B002GWA1D3	SACLE 1:1	REV A0	x±0.35	x°±3.0°	CHECKED BY: TW.Xu
	REMARK:	SHEET 2/3		.xx±0.25	.xx°±1.5°	DESIGN BY: MQ.Qu
				.xxx±0.10	.xxx°±1.0°	

REACH & RoHS  
COMPLIANT

# PROFILE OF WAVE SOLDER

REV.	ECN / DESCRIPTION	BY	DATE
A0	NEW	MQ.Qu	2018.01.11



A.Preheating B.Soldering C.Gradual Cooling  
 Tip temperature:260±5°C.  
 Tip temperature time:5Sec Max.  
 Tip melting point of Sn96.5/Ag3/Cu0.5:217°C.

Remarks: after wave soldering, the plastic positioning columns  
 of the product which under the PCB will be slightly melted,  
 but it won't affect its function.

**WOHU** 苏州沃虎电子科技有限公司  
 Su Zhou Wo Hu Electronic Tech.Co.,Ltd.

TITLE: TAB-DOWN 1X4 100BASE	SIZE A4	UNITS MM[INCH]	GENERAL TOLERANCES UNLESS SPECIFIED		APPROVED BY: JP.Gong
PART NO.: SYT114B002GWA1D3	SACLE 1:1	REV A0	x±0.35	x°±3.0°	CHECKED BY: TW.Xu
REMARK:	SHEET 3/3		.xx±0.25	.xx°±1.5°	DESIGND BY: MQ.Qu
			.xxx±0.10	.xxx°±1.0°	